

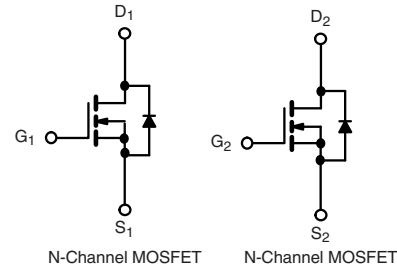
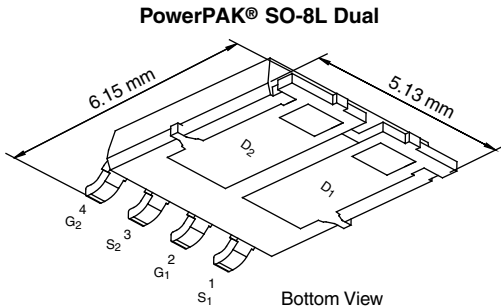
Automotive Dual N-Channel 75 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	75
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.050
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5$ V	0.070
I_D (A) per leg	8
Configuration	Dual

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- AEC-Q101 Qualified^d
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

AUTOMOTIVE GRADE


RoHS
 COMPLIANT
 HALOGEN
FREE


ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ980EP-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	75	V	
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current ^a	I_D	$T_C = 25$ °C	8	
		$T_C = 125$ °C	8	
Continuous Source Current (Diode Conduction) ^a	I_S	8	A	
Pulsed Drain Current ^b	I_{DM}	32		
Single Pulse Avalanche Current	I_{AS}	18		
Single Pulse Avalanche Energy	E_{AS}	L = 0.1 mH	16	mJ
Maximum Power Dissipation ^b			P_D	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	$T_C = 25$ °C	- 55 to + 175	°C
		$T_C = 125$ °C	11	
Soldering Recommendations (Peak Temperature) ^{e, f}			260	

THERMAL RESISTANCE RATINGS			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient	R_{thJA}	85	°C/W
Junction-to-Case (Drain)			

Notes

- Package limited.
- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR4 material).
- Parametric verification ongoing.
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection..
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

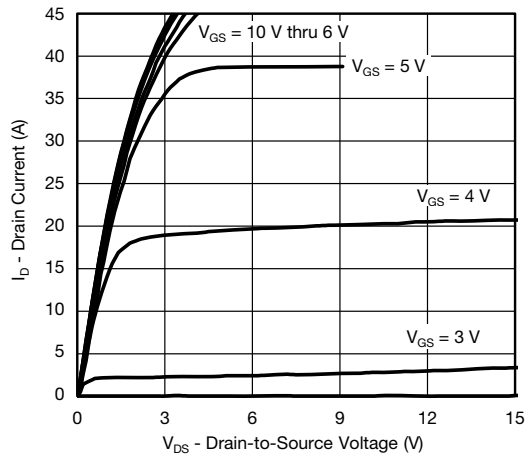
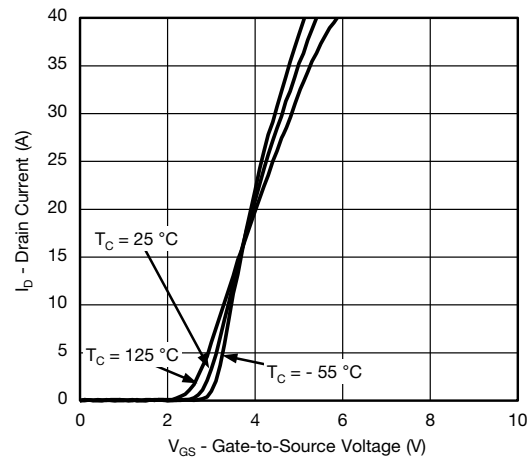
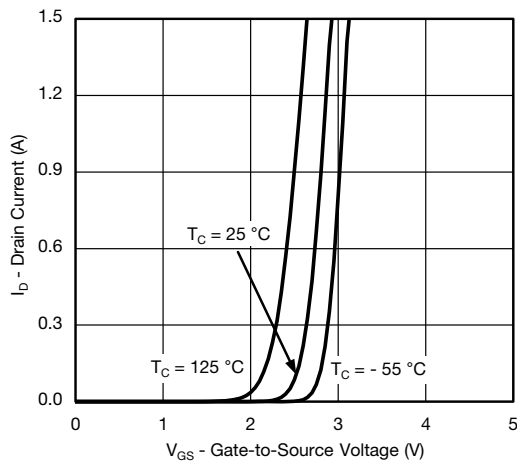
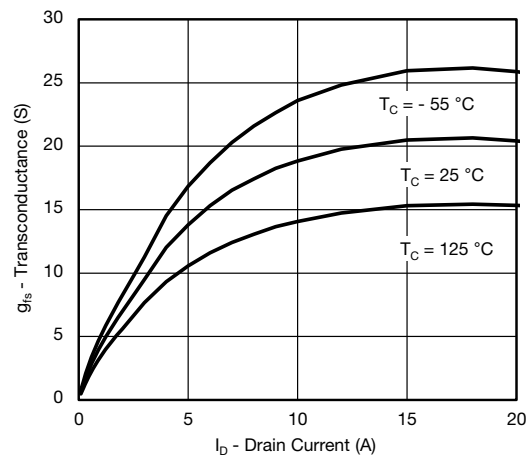
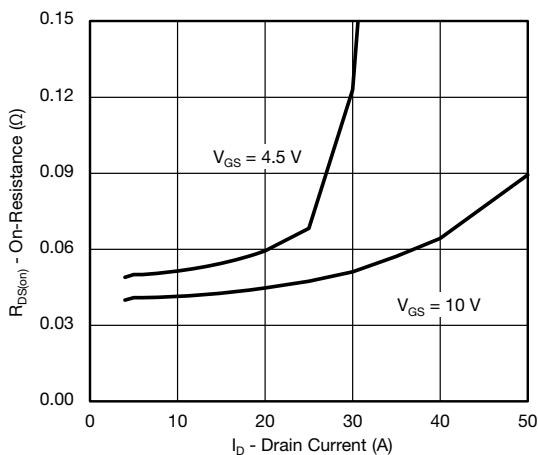
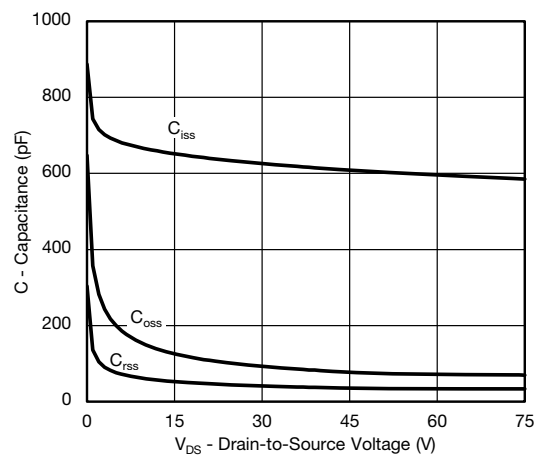


SPECIFICATIONS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$	75	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.5	2.0	2.5	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}$ $V_{DS} = 75\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$ $V_{DS} = 75\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$ $V_{DS} = 75\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	150	
On-State Drain Current ^a	$I_{D(on)}$	$V_{GS} = 10\text{ V}$ $V_{DS} \geq 5\text{ V}$	30	-	-	A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ $I_D = 5\text{ A}$	-	0.041	0.050	Ω
		$V_{GS} = 10\text{ V}$ $I_D = 5\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.092	
		$V_{GS} = 10\text{ V}$ $I_D = 5\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.119	
		$V_{GS} = 4.5\text{ V}$ $I_D = 4.5\text{ A}$	-	0.060	0.070	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 4\text{ A}$	-	12	-	S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$ $V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	630	790	μF
Output Capacitance	C_{oss}		-	100	125	
Reverse Transfer Capacitance	C_{rss}		-	44	55	
Total Gate Charge ^c	Q_g	$V_{GS} = 10\text{ V}$ $V_{DS} = 35\text{ V}, I_D = 9.7\text{ A}$	-	14	21	nC
Gate-Source Charge ^c	Q_{gs}		-	2.3	-	
Gate-Drain Charge ^c	Q_{gd}		-	3.0	-	
Gate Resistance	R_g	$f = 1\text{ MHz}$	1.6	3.2	4.8	Ω
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 35\text{ V}, R_L = 35\text{ }\Omega$ $I_D \cong 1\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	-	8	12	ns
Rise Time ^c	t_r		-	9	14	
Turn-Off Delay Time ^c	$t_{d(off)}$		-	19	29	
Fall Time ^c	t_f		-	8	12	
Source-Drain Diode Ratings and Characteristics^b						
Pulsed Current ^a	I_{SM}		-	-	32	A
Forward Voltage	V_{SD}	$I_F = 4\text{ A}, V_{GS} = 0$	-	0.8	1.1	V

Notes

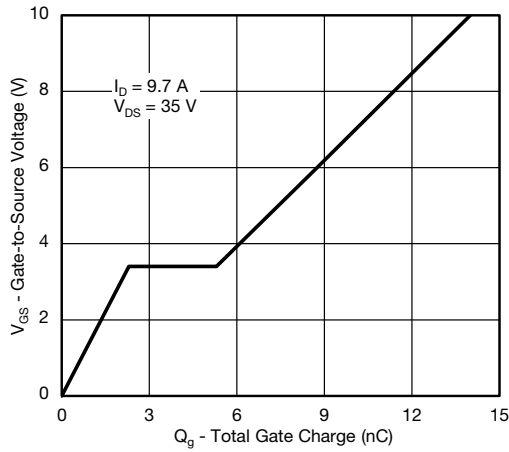
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

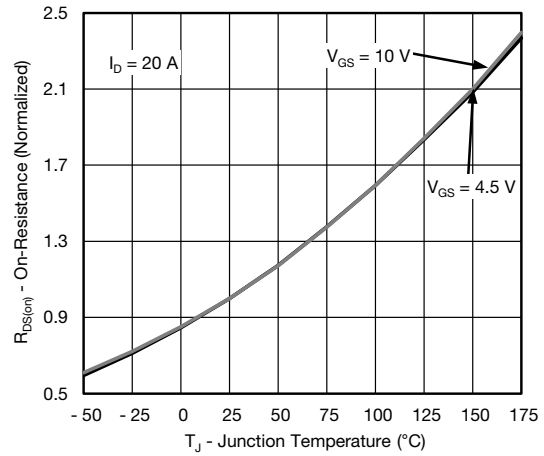
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)

Output Characteristics

Transfer Characteristics

Transfer Characteristics

Transconductance

On-Resistance vs. Drain Current

Capacitance



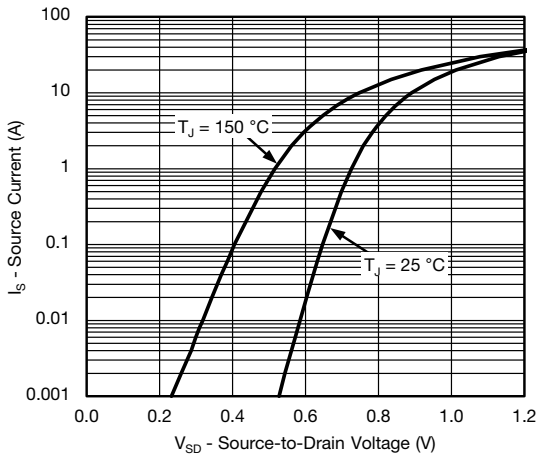
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



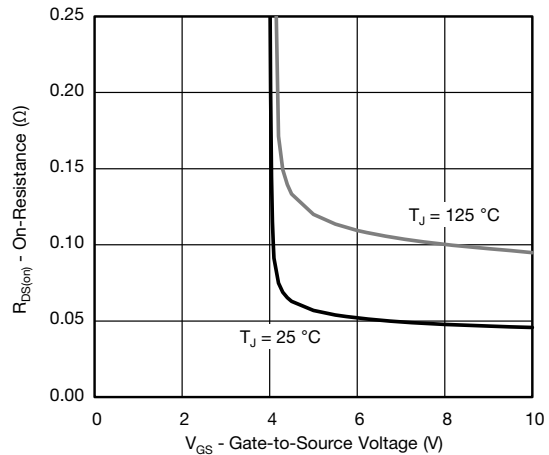
Gate Charge



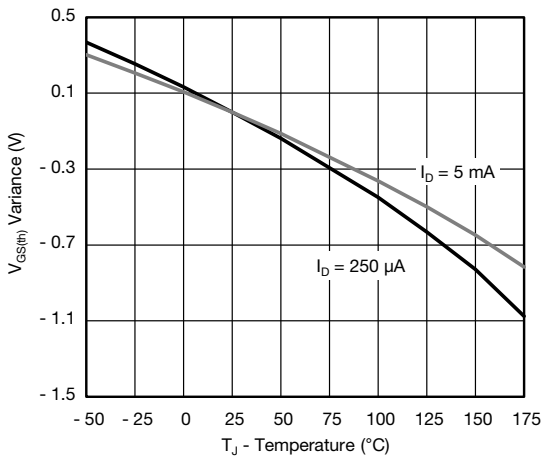
On-Resistance vs. Junction Temperature



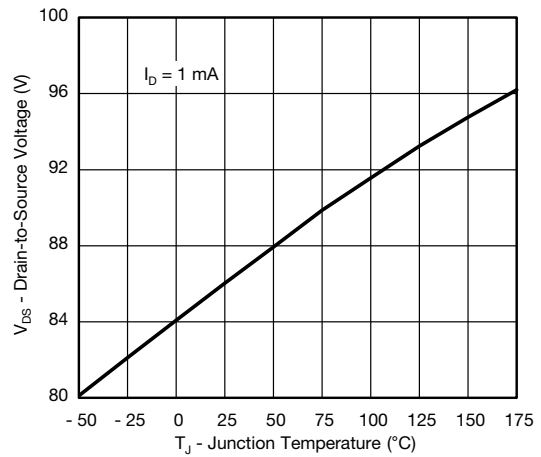
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



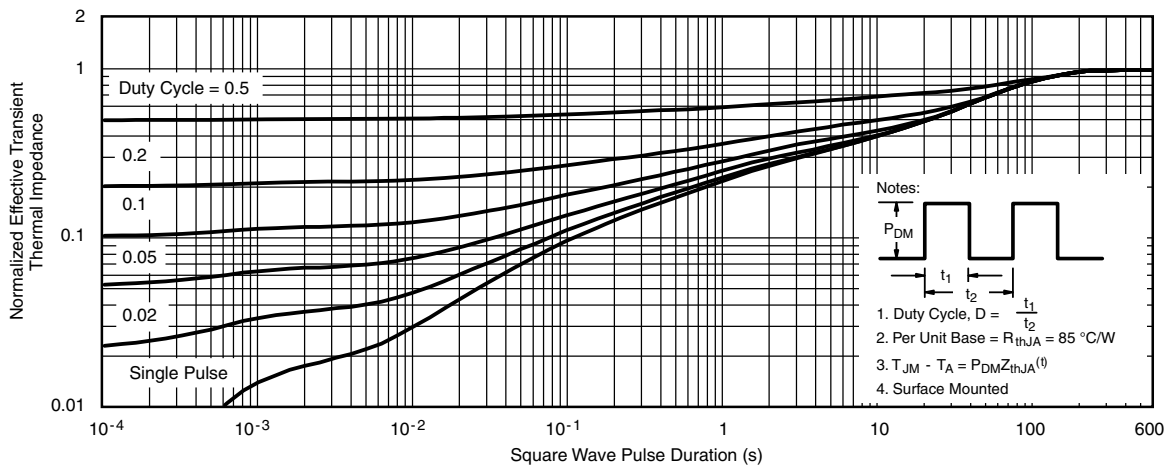
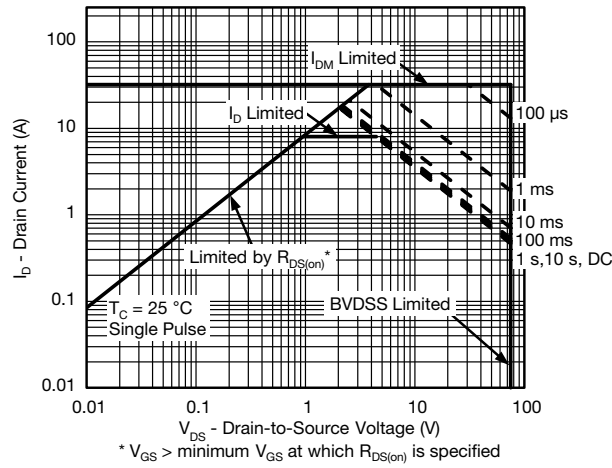
Threshold Voltage

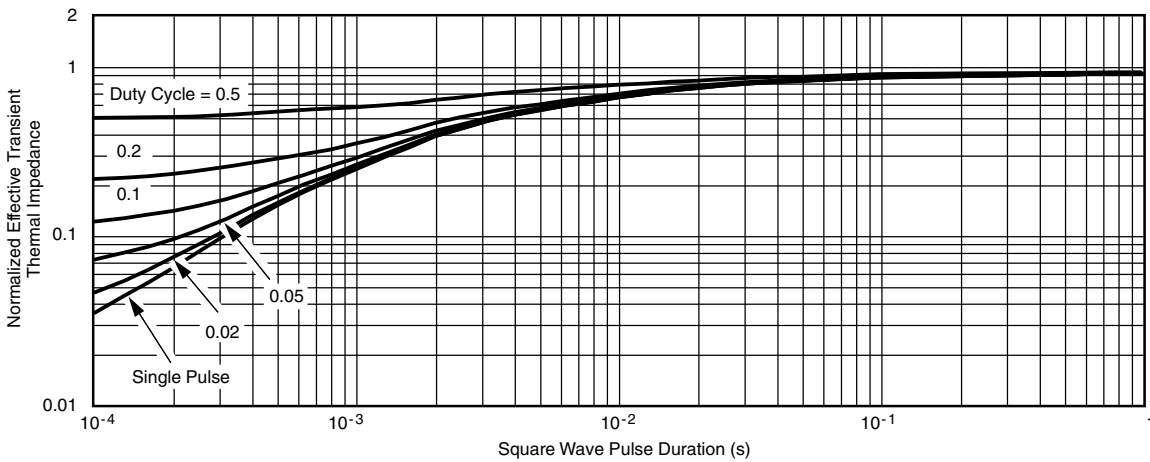


Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Case
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^\circ\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^\circ\text{C}$)
 are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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